

## FEATURES

- \* Ideal for surface mount applications
- \* Easy pick and place
- \* Built-in strain relief
- \* Low forward voltage drop

## MECHANICAL DATA

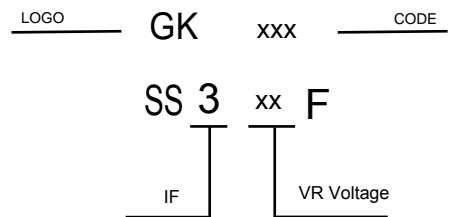
- \* Case: Molded plastic
- \* Epoxy: UL 94V-0 rate flame retardant
- \* Terminals: Solder plated, solderable per MIL-STD-202F method 208 guaranteed
- \* Polarity: Color band denotes cathode end
- \* Mounting position: Any

## VOLTAGE RANGE

150 to 200 Volts

## CURRENT

3.0 Ampere



## MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature unless otherwise specified.  
Single phase half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

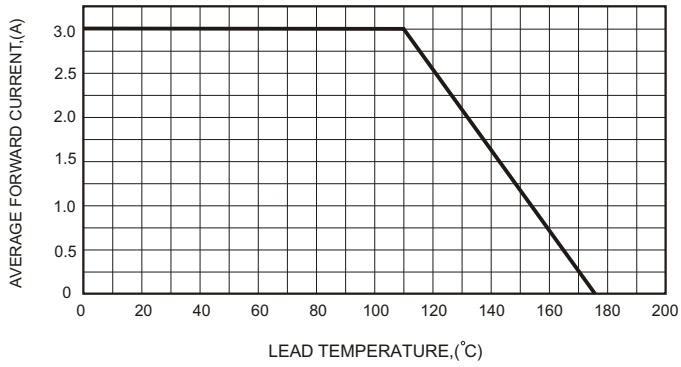
TYPE NUMBER	SS315F	SS320F	UNITS
Maximum Recurrent Peak Reverse Voltage	150	200	V
Maximum RMS Voltage	105	140	V
Maximum DC Blocking Voltage	150	200	V
Maximum Average Forward Rectified Current	3.0		A
Peak Forward Surge Current, 8.3 ms single half sine-wave superimposed on rated load (JEDEC method)	80		A
Maximum Instantaneous Forward Voltage at 3.0A	0.92		V
Maximum DC Reverse Current Ta=25°C	0.02		mA
at Rated DC Blocking Voltage Ta=100°C	2		mA
Typical Junction Capacitance (Note1)	250		PF
Typical Thermal Resistance RθJL (Note 2)	10		°C/W
Operating Temperature Range Tj	-65 — +175		°C
Storage Temperature Range Tstg	-65 — +175		°C

### NOTES:

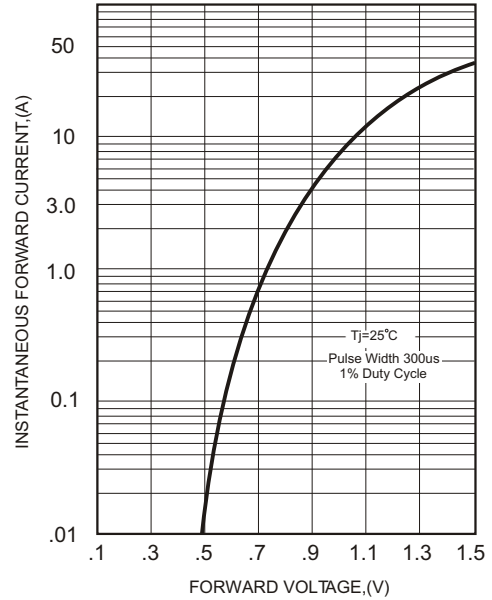
1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2. Thermal Resistance Junction to Lead Vertical PC Board Mounting 0.5"(12.7mm) Lead Length.

**RATING AND CHARACTERISTIC CURVES**

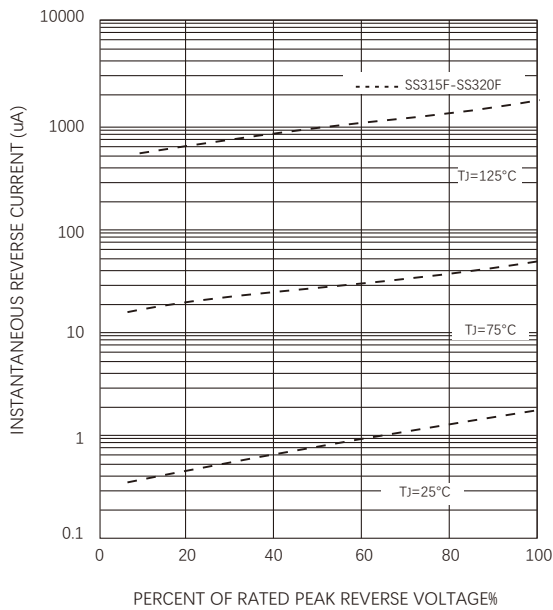
**FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE**



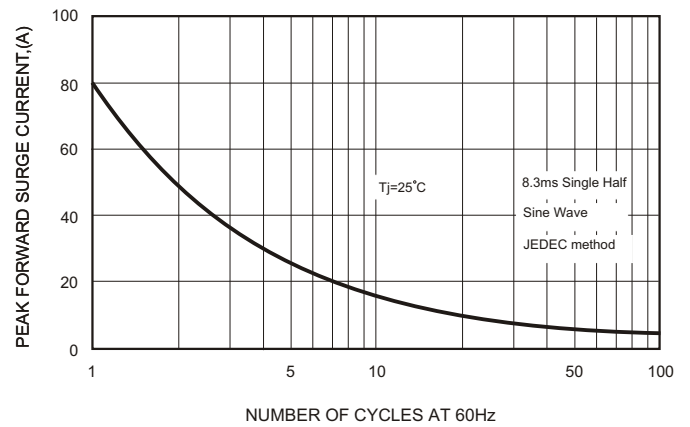
**FIG.2-TYPICAL FORWARD CHARACTERISTICS**



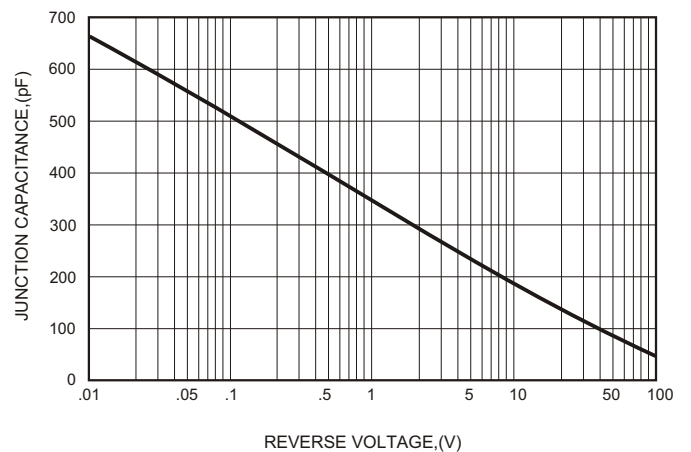
**FIG.3 - TYPICAL REVERSE CHARACTERISTICS**



**FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT**

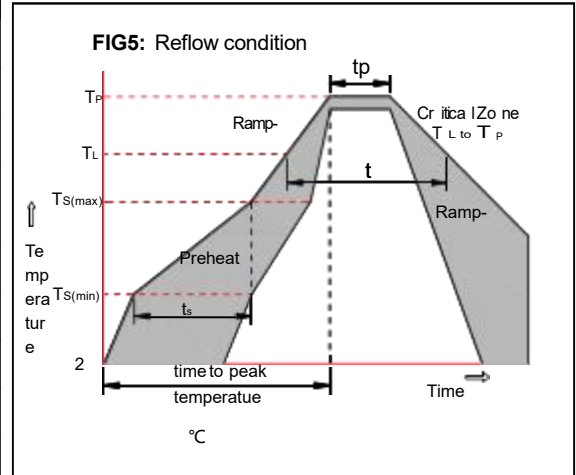


**FIG.5-TYPICAL JUNCTION CAPACITANCE**



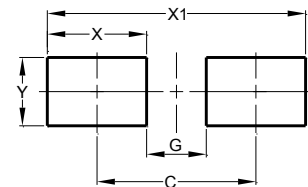
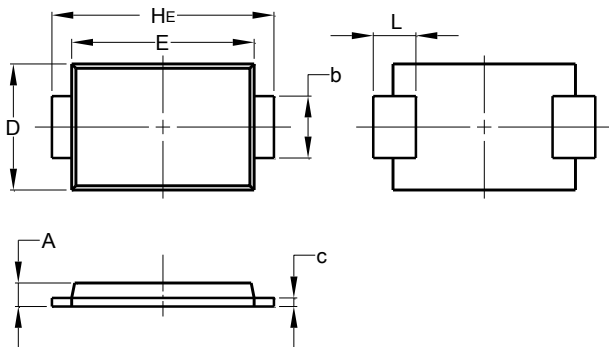
**Soldering parameters**

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ( $T_{s(min)}$ )	+150°C
	-Temperature Max( $T_{s(max)}$ )	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp ( $T_L$ ) to peak)		3°C/sec. Max
$T_{s(max)}$ to $T_L$ - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature( $T_L$ )(Liquid us)	+217°C
	-Temperature( $t_L$ )	60-150 secs.
Peak Temp ( $T_P$ )		+260(+0/-5)°C
Time within 5°C of actual Peak Temp ( $t_p$ )		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp ( $T_P$ )		8 min. Max
Do not exceed		+260°C



**Package Dimensions & Suggested Pad Layout**

**SMAF**



SMAF		
Dim	Min	Max
A	0.90	1.20
b	1.30	1.60
c	0.10	0.20
D	2.40	2.70
E	3.30	3.70
H <sub>E</sub>	4.40	4.90
L	0.60	1.20
All Dimensions in mm		

Dimensions	Value (in mm)
C	3.80
G	2.20
X	1.60
X1	5.40
Y	1.70

Tape & reel specification

Tape		Symbol	Dimension (mm)
		P0	4.00±0.20
		P1	4.00±0.20
		P2	2.00±0.20
		D0	1.55±0.25
		D1	1.55±0.25
		E	1.75±0.20
		F	5.50±0.20
		W	12.00±0.20
		A0	2.85±0.20
		B0	5.00±0.20
		K0	1.45±0.20
		T	0.26±0.10
		7" Reel	
		D3	55.0Min.
		D4	14.0±2.5
		W1	14.0±2.5
		Quantity: 3000PCS	
13" Reel		D5	330.0±5.0
		D6	73.0Min.
		D7	14.0±2.5
		W2	14.0±2.5
		Quantity: 10000PCS	